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A1

area between the chip 32 and the lead frame 30, and thus the lead frame 30 and tape 31 would generate relatively smaller tension stress to the chip 32.

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#### IN THE CLAIMS

Please amend claim 1 as follows:

- A2
1. (Amended) A semiconductor package with a crack-preventing member, comprising:  
a chip carrier;  
at least a chip mounted on the chip carrier and electrically connected to the chip carrier;  
at least a crack-preventing member formed at a predetermined position on the chip and situated substantially on an opposite side of the chip with respect to the chip carrier, for generating compression stress on the chip to counteract tension stress produced from the chip carrier on the chip in a molding process, so as to prevent the chip from cracking; and  
an encapsulant for encapsulating the chip and the crack-preventing member.

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#### REMARKS

Claims 1-15 are pending in the application. Claim 1 has been amended by the present amendment.

Applicants claim a semiconductor package including: a chip carrier; a chip mounted on the chip carrier and electrically connected to the chip carrier; a crack-preventing member situated substantially on an opposite side of the chip with respect to the chip carrier, for generating compression stress on the chip to counteract tension stress produced from the chip carrier on the chip during a molding process and to prevent the chip from cracking; and an encapsulant for encapsulating the chip and the crack-preventing member.

Applicants' invention is exemplified by the following copy of FIG. 2.